

Title (en)

Substrate holder, vertical heat treatment apparatus and heat treatment method

Title (de)

Substrathalter, vertikale Vorrichtung zur Wärmebehandlung und Wärmebehandlungsverfahren

Title (fr)

Support de substrat, appareil de traitement thermique vertical et procédé de traitement thermique

Publication

EP 2375441 A2 20111012 (EN)

Application

EP 11160609 A 20110331

Priority

JP 2010088575 A 20100407

Abstract (en)

A substrate holder 9 includes a pair of right and left front-side support posts 26 and a pair of back-side support posts 27. The front-side support posts 26 and the back-side support posts 27 each have a plurality of grooves 28, 29 which can hold substrates W at a predetermined spacing in the vertical direction and into which the substrates W can be inserted from the front. The support surface 28a on each groove 28 of each front-side support post 26 extends obliquely forward, approaching an anteroposterior center line cl. The distance X2 between wafer support points 30, 30 at the front ends of the support surfaces 28a on opposing grooves 28 of the pair of front-side support posts 26 is equal to the distance Y2 between wafer support points 31, 31 at the front ends of the support surfaces 29a on opposing grooves 29 of the pair of back-side support posts 27.

IPC 8 full level

H01L 21/673 (2006.01)

CPC (source: EP)

H01L 21/67309 (2013.01)

Citation (applicant)

- JP 2008227443 A 20080925 - TOKYO ELECTRON LTD
- JP 2005005379 A 20050106 - SHINETSU HANDOTAI KK

Cited by

CN110246784A

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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